Birla Institute of Technology and Science Pilani K. K. Birla Goa Campus Mid-Semester Examination 2022-23

Heat Transfer (ME F220)

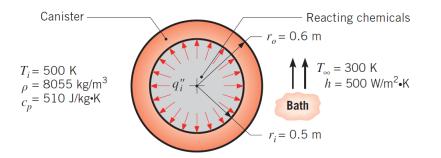
Date:	14-03-2023
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Time: 11.00 AM - 12.30 PM

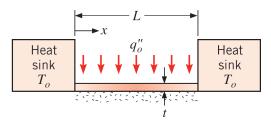
Total Marks: 60

Instruction:

- All questions are compulsory.
- Answer all parts of the question in the same place and start each question in a new page.
- Symbols have their usual meaning.
- Make suitable assumptions whenever necessary. Please state your assumptions clearly.
- Q1. A spherical, stainless steel (AISI 302) canister is used to store reacting chemicals that provide for a uniform heat flux q''_i to its inner surface. The canister is suddenly submerged in a liquid bath of temperature $T_{\infty} < T_i$, where T_i is the initial temperature of the canister wall.



- (a) Assuming negligible temperature gradients in the canister wall and a constant heat flux, de-[10]velop an equation that governs the variation of the wall temperature with time during the transient process. What is the initial rate of change of the wall temperature if $q''_i = 10^5 \text{ W/m}^2$?
- (b) What is the steady-state temperature of the wall?
- Q2. A thin flat plate of length L, thickness t, and width $W \gg L$ is thermally joined to two large heat sinks that are maintained at a temperature T_0 . The bottom of the plate is well insulated, while the net heat flux to the top surface of the plate is known to have a uniform value of q_0'' .



- (a) Derive the differential equation that determines the steady-state temperature distribution T(x)[6]in the plate.
- (b) Solve the foregoing equation for the temperature distribution, and obtain an expression for [6]the rate of heat transfer from the plate to the heat sinks.
- Q3. (a) During a heat treatment process, copper spheres of diameter d are heated to T_i in a furnace [6]and then suddenly cooled to an airstream at a temperature $T_{\infty} < T_i$. The spheres cool due to the convection heat transfer at the solid-liquid interface with a convection coefficient h. Assuming negligible temperature gradients in a sphere, derive the expression for the time trequired to cool the sphere from its initial temperature T_i at t = 0 to some temperature T.

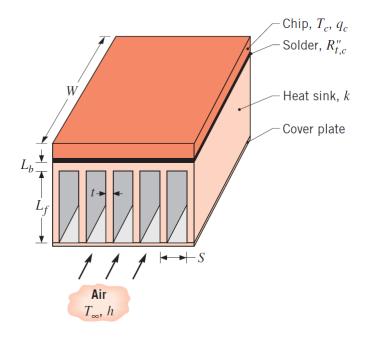
[2]

(b) Consider a sphere of 10 mm diameter is heated to 75 °C and then cooled in an airstream at 23 °C with a velocity of 10 m/s. The convection heat transfer coefficient between the sphere and the air is $116 \text{ W/m}^2 \cdot \text{K}$. Estimate the time required to cool the sphere to a temperature of 30 °C using the expression derived in part (a). The properties of the copper are $\rho = 8933 \text{ kg/m}^3$, $C_p = 387 \text{ J/kg} \cdot \text{K}$

[6]

[12]

Q4. An isothermal square silicon chip of width W = 20 mm on a side is soldered to an aluminum heat sink $(k = 180 \text{ W/m} \cdot \text{K})$ of equivalent width. The heat sink has a base thickness of $L_b = 3 \text{ mm}$ and an array of rectangular fins (N = 11 fins, and thickness t = 0.182 mm), each of length $L_f = 15 \text{ mm}$. Airflow at $T_{\infty} = 20 \,^{\circ}\text{C}$ is maintained through channels formed by the fins and a cover plate, and for a convection coefficient of $h = 100 \text{ W/m}^2 \cdot \text{K}$, a minimum fin spacing of 1.8 mm is dictated by limitations on the flow pressure drop. The solder joint has a thermal resistance of $R''_{t,c} = 2 \times 10^{-6} \text{ m}^2 \cdot \text{K/W}$. If the maximum allowable chip temperature is $T_c = 85 \,^{\circ}\text{C}$, what is the corresponding value of the chip power q_c ? Assume adiabatic fin tip condition. The efficiency of a fin with adiabatic tip is $\eta_f = \tanh(mL)/mL$.



Q5. Answer the following in ONLY One -Two sentences:

(a) Explain the difference between steady state and thermal equilibrium. [2](b) What is the critical radius of insulation? How is it defined for a cylindrical layer? [2](c) Hot water is to be cooled as it flows through the tubes exposed to atmospheric air. Fins are [2]to be attached to enhance heat transfer. Would you recommend attaching the fins inside or outside the tubes? Why? (d) What is a semi-infinite medium? Give examples of solid bodies that can be treated as semi-[2]infinite mediums for heat transfer purposes. (e) Derive an expression for skin layer thickness δ for a semi-infinite body subjected to a sudden [2]change in the surface temperature. (f) Explain when to use the lumped capacitance model, exact solution, and semi-infinite solid [2]approximation based on the dimensionless numbers that describe transient conduction, namely the Biot number (Bi) and the Fourier number (Fo).

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